Attorney Docket No. 021653-014800US

Form PTO-1595 (Rev. 03/05)
OMB No. 0651-0027 (exp. 6/3

07-18-2007

103427836

U.S. DEPARTMENT OF COMMERCE
United States Patent and Trademark Office

ER SHEET
NLY

7-16-07

To the Director of the U. … attached documents or the new address(es) below.

1. Name of conveying party(ies)

Ting Chieh Su
Min Chie Jeng
Chin Chang Liao
Jun Cheng Huang

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: Semiconductor Manufacturing International (Shanghai) Corporation
Internal Address:
Street Address: 18 Zhang Jiang Rd., Pudong New Area
City: Shanghai
State:
Country: People's Republic of China Zip: 201203

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) 02/08/07; 04/10/07; 06/22/07; and 06/22/07 respectively

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

4. Application or patent number(s): ☐ This document is being filed together with a new application.

A. Patent Application No.(s)
11/550,529

B. Patent No.(s)

07/17/200 DBYRNE 00000151 201430 11550529
01 FC:802 40.00 DA

Additional numbers attached? ☐ Yes ☒ No

OFFICE OF PUBLIC RECORDS
2007 JUL 16 PM 3:50
FINANCE SECTION

5. Name and address to whom correspondence concerning document should be mailed:

Name: Daniel Mao
Internal Address:
TOWNSEND AND TOWNSEND AND CREW LLP
Street Address: Two Embarcadero Center, Eighth Floor
City: San Francisco
State: California Zip: 94111-3834
Phone Number: (415) 576-0200
Fax Number: (415) 576-0300
Email Address: DMao@townsend.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) $ 40.00

☐ Authorized to be charged by credit card
☒ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 numbers
Expiration Date

b. Deposit Account Number 20-1430
Authorized User Name Townsend and Townsend and Crew LLP

9. Signature: Daniel Mao
Signature

July 12, 2007
Date

Daniel Mao
Name of Person Signing Atty. Reg. No. 51,995

Total number of pages including cover sheet, attachments, and documents: 6

Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, VA 22313-1450

Attorney Docket No.: 021653-014800US
Client Reference No.: I-04-228

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, **Ting Chieh Su** of No. 61, Guang Ming 5th Rd., Nantou, Taiwan; **Min Chie Jeng** of 1F, 118, Lane 249 Yuan Yuan Road, Keelung, Taiwan; **Chin Chang Liao** of 18 Zhang Jiang Rd. Pudong New Area, Shanghai, 201203 People's Republic of China; and **Jun Cheng Huang** of 18 Zhang Jiang Rd. Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: **SYSTEM AND METHOD FOR I/O ESD PROTECTION WITH POLYSILICON REGIONS FABRICATED BY PROCESSES FOR MAKING CORE TRANSISTORS**

Filing Date: **October 18, 2006**

Application No.: **11/550,529**; and

WHEREAS, **Semiconductor Manufacturing International (Shanghai) Corporation**, a corporation of People's Republic of China, located at 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: 2/8, 2007 ______________________
Ting Chieh Su

Dated: ______________________ ______________________
Min Chie Jeng

Dated:________________________ ____________________________________
Chin Chang Liao

Dated:________________________ ____________________________________
Jun Cheng Huang

60965132 v1

Attorney Docket No.: 021653-014800US
Client Reference No.: I-04-228

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, **Ting Chieh Su** of No. 61, Guang Ming 5th Rd., Nantou, Taiwan; **Min Chie Jeng** of 1F, 118, Lane 249 Yuan Yuan Road, Keelung, Taiwan; **Chin Chang Liao** of 18 Zhang Jiang Rd. Pudong New Area, Shanghai, 201203 People's Republic of China; and **Jun Cheng Huang** of 18 Zhang Jiang Rd. Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention:	**SYSTEM AND METHOD FOR I/O ESD PROTECTION WITH POLYSILICON REGIONS FABRICATED BY PROCESSES FOR MAKING CORE TRANSISTORS**
Filing Date:	**October 18, 2006**
Application No.:	**11/550,529**; and

WHEREAS, **Semiconductor Manufacturing International (Shanghai) Corporation**, a corporation of People's Republic of China, located at 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: ____________________ ____________________
Ting Chieh Su

Dated: Apr. 10 2007 ____________________
Min Chie Jeng

Attorney Docket No.: 021653-014800US
Client Reference No.: I-04-228

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, **Ting Chieh Su** of No. 61, Guang Ming 5th Rd., Nantou, Taiwan; **Min Chie Jeng** of 1F, 118, Lane 249 Yuan Yuan Road, Keelung, Taiwan; **Chin Chang Liao** of 18 Zhang Jiang Rd. Pudong New Area, Shanghai, 201203 People's Republic of China; and **Jun Cheng Huang** of 18 Zhang Jiang Rd. Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention:	**SYSTEM AND METHOD FOR I/O ESD PROTECTION WITH POLYSILICON REGIONS FABRICATED BY PROCESSES FOR MAKING CORE TRANSISTORS**
Filing Date:	**October 18, 2006**
Application No.:	**11/550,529**; and

WHEREAS, **Semiconductor Manufacturing International (Shanghai) Corporation**, a corporation of People's Republic of China, located at 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated:____________________ ____________________________
Ting Chieh Su

Dated:____________________ ____________________________
Min Chie Jeng

Dated: 6/22/2007 Chin Chang Liao
Chin Chang Liao

Dated: 6/22/2007
Jun Cheng Huang

60965132 v1